

S102S03/S202S03

SIP Type SSR with Mounting Capability for External Heat Sink

■ Features

1. High radiation resin mold package
2. RMS ON-state current I_T : MAX. 8 Arms at $T_c \leq 80^\circ\text{C}$ (With heat sink)
3. Isolation voltage between input and output (V_{iso} : 4 000V_{rms})
4. Low input driving current (I_{IF} : MAX. 5mA)
5. Approved by CSA, No. LR63705
Recognized by UL, file No. E94758

■ Applications

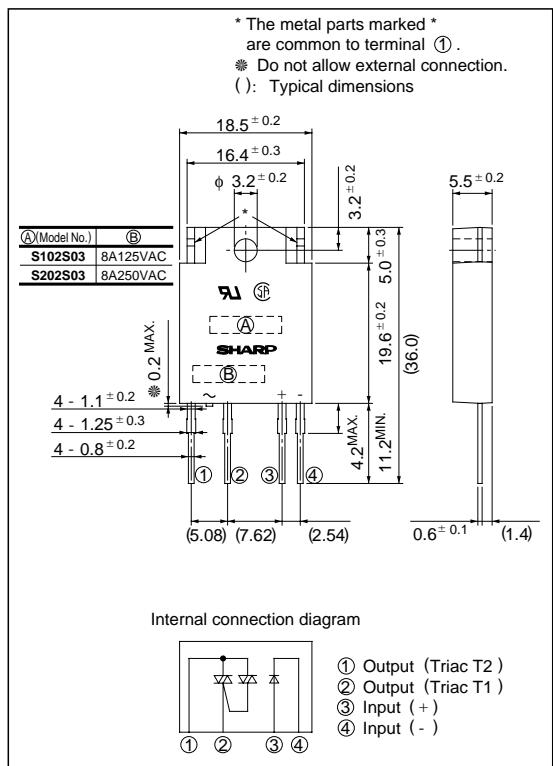
1. Automatic vending machines
2. Programmable controllers
3. Amusement equipment

■ Model Line-ups

For 100V lines	For 200V lines
S102S03	S202S03

■ Outline Dimensions

(Unit : mm)



■ Absolute Maximum Ratings

 $(Ta = 25^\circ\text{C})$

Parameter	Symbol	Rating		Unit
		S102S03	S202S03	
Input	Forward current	I_F	50	mA
	Reverse voltage	V_R	6	V
Output	RMS ON-state current	I_T	[*] 48	A _{rms}
	[*] Peak one cycle surge current	I_{surge}	80	A
	Repetitive peak OFF-state voltage	V_{DRM}	400	V
	Non-repetitive peak OFF-state voltage	V_{DSM}	400	V
	Critical rate of rise of ON-state current	dI_T/dt	50	A/ μ s
	Operating frequency	f	45 to 65	Hz
	[*] 2 Isolation voltage	V_{iso}	4 000	V _{rms}
	Operating temperature	T_{opr}	-25 to +100	°C
	Storage temperature	T_{stg}	-30 to +125	°C
	[*] 3 Soldering temperature	T_{sol}	260	°C
	When the isolation voltage is necessary at using external heat sink, please use the insulation sheet.			
	[*] 3 For 10 seconds			
[*] 4 $T_c \leq 80^\circ\text{C}$				

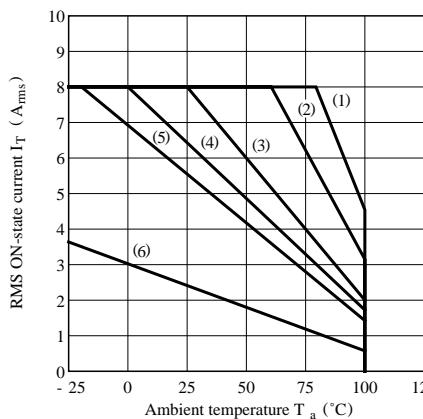
^{*} In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that occur in equipment using any of SHARP's devices, shown in catalogs, data books, etc. Contact SHARP in order to obtain the latest version of the device specification sheets before using any SHARP's device."

■ Electro-optical Characteristics

(Ta = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	V _F	I _F = 20mA	-	1.2	1.4	V
	Reverse current	I _R	V _R = 3V	-	-	10 ⁻⁴	A
Output	Repetitive peak OFF-state current	I _{DRM}	V _D = V _{DRM}	-	-	10 ⁻⁴	A
	On-state voltage	V _T	Resistance load, I _F = 20mA I _T = 2A _{rms}	-	-	1.5	V _{rms}
	Holding current	I _H	-	-	-	35	mA
	Critical rate of rise of OFF-state voltage	dV/dt	V _D = 2/3V _{DRM}	30	-	-	V/ μ s
	Critical rate of rise of commutating OFF-state voltage	(dV/dt) _C	T _j = 125°C, dI _t /dt = - 4.0A/ms, V _D = 400V	5	-	-	V/ μ s
Transfer characteristics	Minimum trigger current	I _{FT}	V _D = 12V, R _L = 30Ω	-	-	5	mA
	Isolation resistance	R _{ISO}	DC = 500V, 40 to 60% RH	10 ¹⁰	-	-	Ω
	Turn-on time	t _{on}	AC = 50Hz	-	-	1	ms
	Turn-off time	t _{off}		-	-	10	ms
Thermal resistance (Between junction and case)		R _{th(j - c)}	-	-	4.5	-	°C/W
Thermal resistance (Between junction and ambience)		R _{th(j - a)}	-	-	40	-	°C/W

**Fig. 1 RMS ON-state Current vs.
Ambient Temperature**



- (1) With infinite heat sink
 - (2) With heat sink (200 x 200 x 2 mm Al plate)
 - (3) With heat sink (100 x 100 x 2 mm Al plate)
 - (4) With heat sink (75 x 75 x 2 mm Al plate)
 - (5) With heat sink (50 x 50 x 2 mm Al plate)
 - (6) Without heat sink
- (Note) With the Al heat sink set up vertically, tighten the device at the center of the Al heat sink with a torque of 0.4N·m and apply thermal conductive silicone grease on the heat sink mounting plate. Forcible cooling shall not be carried out.

Fig. 2 RMS ON-state Current vs. Case Temperature

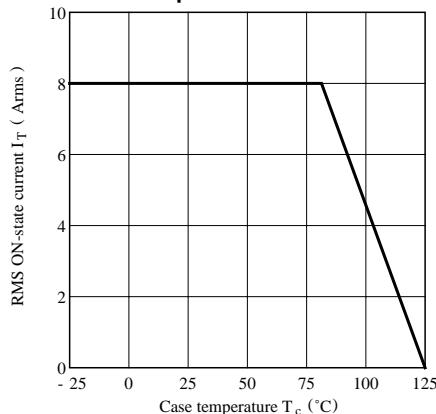


Fig. 3 Forward Current vs. Ambient Temperature

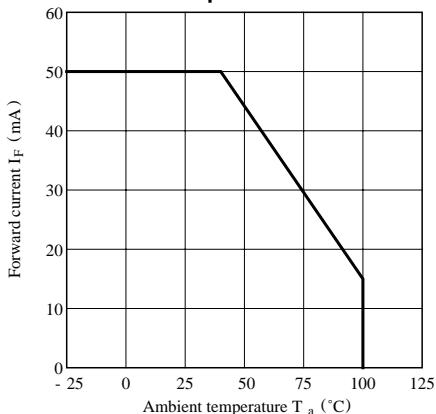


Fig. 4 Forward Current vs. Forward Voltage

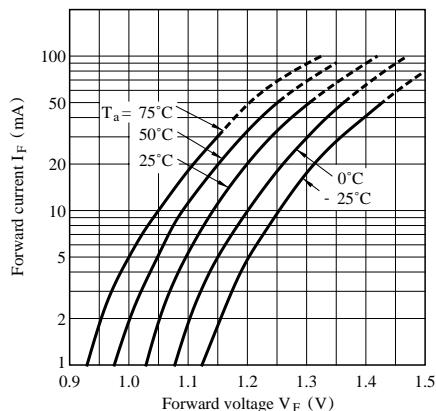


Fig. 5 Surge Current vs. Power-on Cycle

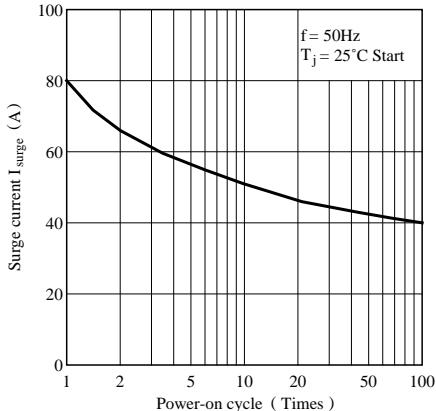


Fig. 6 Maximum ON-state Power Dissipation vs. RMS ON-state Current (Typical Value)

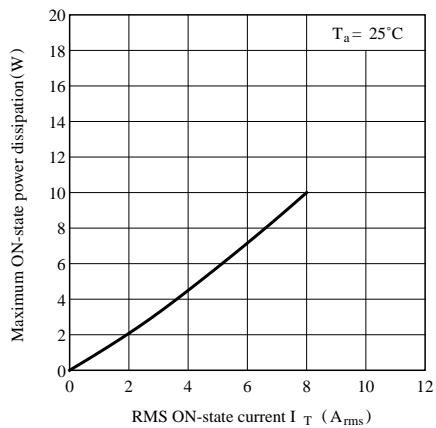


Fig. 7 Minimum Trigger Current vs. Ambient Temperature (Typical Value)

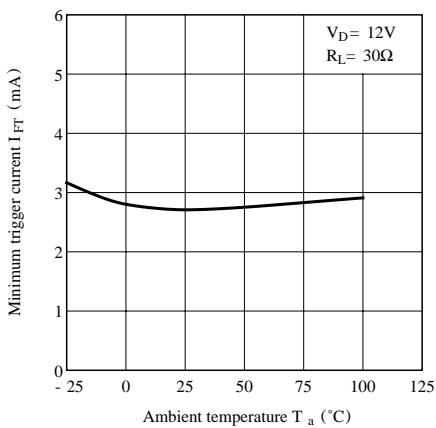


Fig.8-a Repetitive Peak OFF-state Current vs. Ambient Temperature (Typical Value) (S102S03)

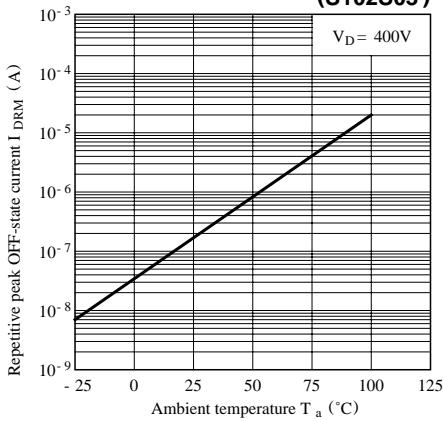
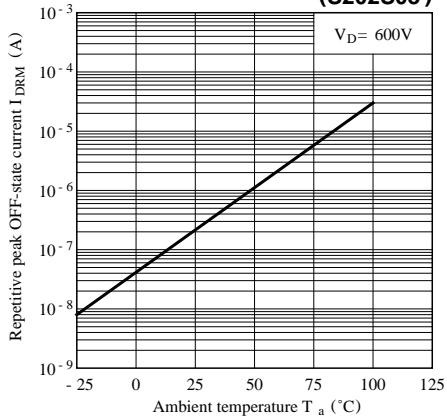


Fig.8-b Repetitive Peak OFF-state Current vs. Ambient Temperature (Typical Value) (S202S03)



- Please refer to the chapter “Precautions for Use”